

	Type	L #	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r D e f i n i t i o n	E r r o r s
1	BRS	L1	333	(clean\$3 or polish\$3) same (semiconductor or substrate) same (nozzle or "liquid source" or outlet) same (angle or disance or length or gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:23			0
2	BRS	L8	156	1 and @pd<=19980618	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:29			0
3	BRS	L15	70	rins\$3 same (semiconductor or substrate) same (nozzle or "liquid source" or outlet) same (angle or disance or length or gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:26			0
4	BRS	L22	29	15 and @pd<=19980618	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/14 11:29			0

	Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s	E r r o r s
1	BRS	2179	ultrasonic same (rins\$3 or clean\$3) same (smeicondcutor or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:09			0
2	BRS	2179	ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:09			0
3	BRS	2710	ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 17:42			0
4	BRS	1490	(ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)) and @pd<=19980618	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:09			0
5	BRS	141	((ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)) and @pd<=19980618) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:09			0
6	BRS	40	((ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)) and @pd<=19980618) and 156/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:09			0
7	BRS	164	((ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)) and @pd<=19980618) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:10			0
8	BRS	5	(ultrasonic same (rins\$3 or clean\$3) same (semiconductor or substrate)) same splash	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:06			0
9	BRS	735	clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:08			0
10	BRS	414	(clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:36			0

	Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r s
11	BRS	12	((clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618) and 156/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:10		0
12	BRS	44	((clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:12		0
13	BRS	11	((clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618) and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:10		0
14	BRS	12	((clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:10		0
15	BRS	42	((clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618) and 134/\$.ccls.) not (((clean\$3 same rate same (rotat\$5 or flow of distance or time) same (parameters or variables)) and @pd<=19980618) and 156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:34		0
16	BRS	376	(semiconductor or wafer or substrate) and clean\$3 and (liquid same distance same mm)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:43		0
17	BRS	160	((semiconductor or wafer or substrate) and clean\$3 and (liquid same distance same mm)) and @pd<=19980618	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:47		0
18	BRS	9161	(semiconductor or wafer or substrate) and clean\$3 and (((liquid or delivery) adj source) or nozzle) and (distance or mm or degrees or angle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:46		0
19	BRS	389	(semiconductor or wafer or substrate) same clean\$3 same (((liquid or delivery) adj source) or nozzle) same (distance or mm or degrees or angle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:47		0

	Type	Hits	Search Text	DBs	Time Stamp	C o m m e n t s	E r r o r D e f i n i t i o n	E r r o r s
20	BRS	177	((semiconductor or wafer or substrate) same clean\$3 same (((liquid or delivery) adj source) or nozzle) same (distance or mm or degrees or angle)) and @pd<=19980618	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/13 18:47			0